Product Bulletin

Document #:PB23361X
Issue Date:10 Jun 2020

Title of Change:	AR1337 Datasheet Update.
Effective date:	10 Jun 2020
Contact information:	Contact your local ON Semiconductor Sales Office or Sonya.Yip@onsemi.com
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Documentation Change
Change Sub-Category(s):	Datasheet/Product Doc change

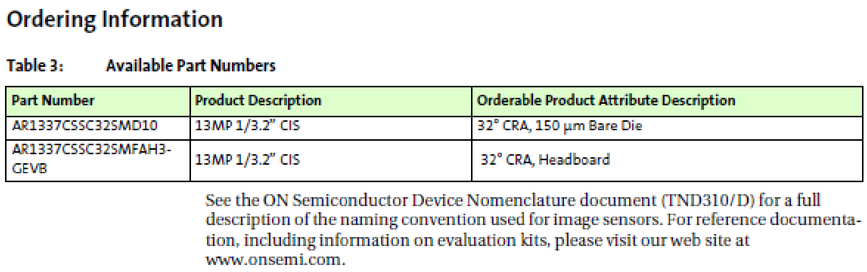
Sites Affected:

ON Semiconductor Sites	**External Foundry/Subcon Sites**
None	None

Description and Purpose:

1. Updated Table 3, "Available Part Numbers"

Old Table 3:



Ordering Information

Table 3: Available Part Numbers

Part Number	Product Description	Orderable Product Attribute Description
AR1337CSSC32SMD10	13MP 1/3.2" CIS	32° CRA, 150 µm Bare Die
AR1337CSSC32SMFAH3-GEVB	13MP 1/3.2" CIS	32° CRA, Headboard

See the ON Semiconductor Device Nomenclature document (TND310/D) for a full description of the naming convention used for image sensors. For reference documentation, including information on evaluation kits, please visit our web site at www.onsemi.com.

New Table 3:

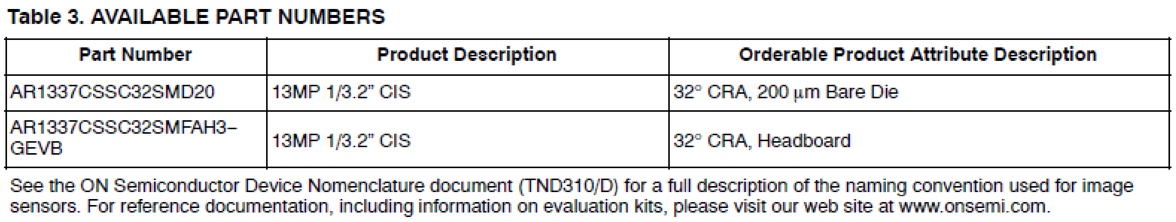


Table 3. AVAILABLE PART NUMBERS

Part Number	Product Description	Orderable Product Attribute Description
AR1337CSSC32SMD20	13MP 1/3.2" CIS	32° CRA, 200 µm Bare Die
AR1337CSSC32SMFAH3–GEVB	13MP 1/3.2" CIS	32° CRA, Headboard

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List of Affected Standard Parts:

***Note**: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.*

AR1337CSSC32SMD10
AR1337CSSC32SMD20